

inal power dissipation of 5.5W.

PART

MAX1150AIZS

MAX1150BIZS

General Description

Ordering Information

PIN-PACKAGE

80 MQUAD

80 MQUAD

The MAX1150 is a parallel flash analog-to-digital con-

verter (ADC) capable of digitizing full-scale (OV to

-2V) inputs into 8-bit digital words at an update rate of

500Msps. The ECL-compatible outputs are demuxed into two separate output banks, each with differential

data-ready outputs to ease the task of data capture.

The MAX1150's wide input bandwidth and low capacitance eliminate the need for external track/hold amplifiers for most applications. A proprietary decoding

scheme reduces metastable errors to 1LSB. This device operates from a single -5.2V supply, with a nom-

TEMP. RANGE

-20°C to +85°C

-20°C to +85°C

8-Bit, 500Msps Flash ADC

Features

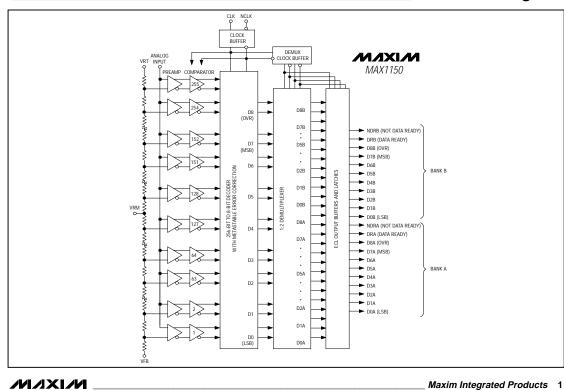
- 1:2 Demuxed ECL-Compatible Outputs
- Wide Input Bandwidth: 900MHz
- Low Input Capacitance: 15pF
- Metastable Errors Reduced to 1LSB
- Single -5.2V Supply

__Applications

Digital Oscilloscopes Data Acquisition Transient-Capture Applications Radar, EW, ECM Direct RF/IF Downconversion

Pin Configuration appears on last page.

Functional Diagram



For the latest literature: http://www.maxim-ic.com, or phone 1-800-998-8800

MAX1150

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ABSOLUTE MAXIMUM RATINGS

Supply Voltages

Supply voltages	
Negative Supply Voltage (VEE to GND)	7.0V to +0.5V
Ground Voltage Differential	0.5V to +0.5V
nput Voltages	
Analog Input Voltage	+0.5V to VEE
Reference Input Voltage	+0.5V to V _{EE}
Digital Input Voltage	+0.5V to V _{EE}

Digital Output Current	0mA to -28mA
Operating Temperature Range	20°C to +85°C
Case Temperature	+125°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10sec)	+300°C
Storage Temperature Range	65°C to +150°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{EE} = -5.2V, V_{RB} = -2.00V, V_{RM} = -1.00V, V_{RT} = 0.00V, f_{CLK} = 500MHz, duty cycle = 50\%, typical thermal impedance (<math>\theta_{JC}$) = 4°C/W, $T_{J} = T_{C} = T_{A} = +25$ °C.) (Note 1)

PARAMETER	CONDITIONS	TEST	MAX1150A		MAX1150B			UNITS		
PARAMETER	CONDITIONS	LEVEL	MIN	TYP	MAX	MIN	TYP	MAX	UNITS	
Resolution				8			8		Bits	
DC ACCURACY										
Integral Nonlinearity	f _{CLK} = 100kHz	I	-1.0		1.0	-1.5		1.5	LSB	
Differential Nonlinearity	f _{CLK} = 100kHz	I	-0.85		0.95	-0.95		1.5	LSB	
No Missing Codes			(Guarantee	d	Guaranteed				
ANALOG INPUT										
Input Voltage Range		I	V_{RB}		V _{RT}	V _{RB}		V _{RT}	V	
Input Bias Current	$V_{IN} = 0V$	I		0.75	2.0		0.75	2.0	mA	
Input Resistance		V		15			15		kΩ	
Input Capacitance	Over full input range	V		15			15		рF	
Input Dandwidth	Small signal	V		900			900		N 41 1-	
Input Bandwidth	Large signal	V		500			500		– MHz	
Offset Error V _{RT}		IV	-30		30	-30		30	mV	
Offset Error V _{RB}		IV	-30		30	-30		30	mV	
Input Slew Rate		V		5			5		V/ns	
REFERENCE INPUT									•	
Ladder Resistance		I	60	80		60	80		Ω	
Reference Bandwidth		V		30			30		MHz	
TIMING CHARACTERISTIC	S									
Maximum Sample Rate		I	500			500			MHz	
Aperture Jitter		V		2			2		ps	
Acquisition Time		V		250			250		ps	
CLK to DATA READY Delay		IV	0.9	1.4	1.9	0.9	1.4	1.9	ns	
Clock to Data Delay		IV	1.25	1.75	2.25	1.25	1.75	2.25	ns	

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ELECTRICAL CHARACTERISTICS (continued)

 $(V_{EE} = -5.2V, V_{RB} = -2.00V, V_{RM} = -1.00V, V_{RT} = 0.00V, f_{CLK} = 500MHz, duty cycle = 50\%, typical thermal impedance (<math>\theta_{JC}$) = 4°C/W, T_J = T_C = T_A = +25°C.) (Note 1)

PARAMETER	CONDITIONS	TEST LEVEL	MIN	MAX1150 TYP	A MAX	MIN	MAX1150 TYP	B MAX	UNITS
		LEVEL	MIN	ITP	MAX	IVIIN	ITP	WAX	
DYNAMIC PERFORMANC									
Signal-to-Noise Ratio	$f_{IN} = 50MHz$		47			45			dB
(without harmonics)	$f_{IN} = 250MHz$	I	44			42			
Total Harmonic Distortion	fin = 50MHz	I	-46			-44			dBc
	fin = 250MHz	I	-38			-36			abe
Signal-to-Noise and	$f_{IN} = 50MHz$	I	43			41			dB
Distortion	$f_{IN} = 250MHz$	I	37			35			
Spurious-Free Dynamic	$f_{IN} = 50MHz$	I	49			44			dB
Range	f _{IN} = 250MHz	I	41			36			
DIGITAL INPUTS									
Input High Voltage (CLK, NCLK)		I	-1.1	-0.7		-1.1	-0.7		V
Input Low Voltage (CLK, NCLK)		I		-1.8	-1.5		-1.8	-1.5	V
Clock Pulse Width High (t _{PWH})		I	1.0	0.67		1.0	0.67		ns
Clock Pulse Width Low (t _{PWL})		I	1.0	0.67		1.0	0.67		ns
Clock Synchronous Input Currents		V		2			2		μΑ
DIGITAL OUTPUTS	I								
Logic "1" Voltage			-1.1	-0.9		-1.1	-0.9		V
Logic "0" Voltage				-1.8	-1.5		-1.8	-1.5	V
POWER-SUPPLY REQUIR	EMENTS	1							
Supply Voltage (VEE)		IV	-4.95	-5.2	-5.45	-4.95	-5.2	-5.45	V
Supply Current (I _{FF})				1.05	1.2		1.05	1.2	A
Power Dissipation				5.5	6.25		5.5	6.25	W
				0.0	0.20		0.0	0.20	v v

Note 1: All parameters having min/max specifications are guaranteed. The Test Level column indicates the specific device test actually performed during production and Quality Assurance inspection. Unless otherwise noted, all tests are pulsed tests; therefore, $T_j = T_C = T_A$.

TEST LEVEL TEST PROCEDURE

- I 100% production tested at the specified temperature.
- II 100% production tested at $T_A = +25$ °C, and sample tested at the specified temperatures.
- III QA sample tested only at the specified temperatures.
- IV Parameter is guaranteed (but not tested) by design and characterization data.
- V Parameter is a typical value for information purposes only.
- VI 100% production tested at $T_A = +25$ °C. Parameter is guaranteed over specified temperature range.

		Pin Description
PIN	NAME	FUNCTION
1, 2, 3	D2B, D3B, D4B	Data Output Bank, Bits 2, 3, and 4
4, 5, 19, 20, 22, 23, 27, 28, 38, 39, 40, 46, 47, 49, 60, 67, 79	VEE	Negative Supply, nominally -5.2V
6	D5B	Data Output Bank B, Bit 5
7, 9, 11, 54, 56, 58, 69, 71, 73, 75, 77	DGND	Digital Ground
8	D6B	Data Output Bank B, Bit 6
10	D7B	Data Output Bank B, Bit 7 (MSB)
12	D8B	Data Output Bank B, Bit 8 (OVR)
13, 14, 31, 34, 41, 63, 64	N.C.	No Connection. Not internally connected.
15–18, 25, 26, 29, 30, 36, 37, 44, 45, 51, 52	AGND	Analog Ground
21	VRBF	Reference-Voltage Force Bottom
24	VRBS	Reference-Voltage Sense Bottom
32, 33	VIN	Analog Input Voltage. Can be either voltage or sense.
35	VRM	Reference-Voltage Middle, nominally -1V
42	VRTF	Reference-Voltage Force Top
43	VRTS	Reference-Voltage Sense Top
48	NCLK	Inverse Clock Input
50	CLK	Clock Input
53	DRA	Data Ready Bank A
55	NDRA	Not Data Ready Bank A
57	D0A	Data Output Bank A, Bit 0 (LSB)
59, 61, 62, 65, 66, 68	D1A-D6A	Data Output Bank A, Bits 1–6
70	D7A	Data Output Bank A, Bit 7 (MSB)
72	D8A	Data Output Bank A, Bit 8 (OVR)
74	NDRB	Not Data Ready Bank B
76	DRB	Data Ready Bank B
78	D0B	Data Output Bank B, Bit 0 (LSB)
80	D1B	Data Output Bank B, Bit 1

_Detailed Description

The MAX1150 is one of the fastest monolithic, 8-bit, parallel, flash analog-to-digital converters (ADCs) available today. The nominal conversion rate is 500Msps, and the analog bandwidth is in excess of 900MHz. A major advance over previous flash converters is the inclusion of 255 input preamplifiers between the reference ladder and input comparators (see *Functional Diagram*). This not only reduces clock transient kickback to the input and reference ladder, but also reduces the effect of the input signal's dynamic state on the input comparators' latching characteristics. The preamplifiers act as buffers to stabilize the input capacitance so that it remains constant over different input voltage and frequency ranges, making the part easier to drive than previous flash converters. The preamplifiers also add a gain of +2 to the input signal, so that each comparator has a wider overdrive or threshold range to trip into or out of the active state. This gain reduces metastable states that can cause errors at the output.

M/IXI/M

The MAX1150 has true differential analog and digital data paths from the preamplifiers to the output buffers (current-mode logic) for reducing potential missing codes while rejecting common-mode noise.

Signature errors are also reduced by careful layout of the analog circuitry. The device's output drive capability can provide full ECL swings into 50Ω loads.

Typical Interface Circuit

The circuit of Figure 1 shows a method of achieving the least error by correcting for integral linearity, inputinduced distortion, and power- supply/ground noise. This is achieved with the use of external reference-ladder tap connections, an input buffer, and supply decoupling. Contact the factory for the MAX1150/MAX1151 evaluation kit manual, which contains more details on interfacing the MAX1150. The function of each pin and external connections to other components are described in the following sections.

VEE, AGND, DGND

VEE is the supply pin with AGND as ground for the device. The power-supply pins should be bypassed as close to the device as possible with at least a 0.01μ F ceramic capacitor. A 1µF tantalum can also be used for low-frequency suppression. DGND is the ground for the ECL outputs, and should be referenced to the output pulldown voltage and appropriately bypassed, as shown in Figure 1.

VIN (Analog Input)

There are two analog input pins that are tied to the same point internally. Either one may be used as an analog input sense, while the other is used for input force. This is convenient for testing the source signal to see if there is sufficient drive capability. The pins can also be tied together and driven by the same source. The MAX1150 is superior to similar devices due to a preamplifier stage before the comparators. This makes the device easier to drive because it has constant capacitance and induces less slew-rate distortion.

CLK, NCLK (Clock Inputs)

The clock inputs are designed to be driven differentially with ECL levels. The duty cycle of the clock should be kept at 50%, to avoid causing larger second harmonics. If this is not important to the intended application, duty cycles other than 50% may be used.

D0 to D8, DR, NDR (A and B)

The digital outputs can drive 50Ω to ECL levels when pulled down to -2V. When pulled down to -5.2V, the outputs can drive 130Ω to $1k\Omega$ loads. All digital outputs are gray code, with the coding as shown in Table 1.



Table 1. Outp	D8	D7 D0
V _{IN} (V) 0	1	1000000 1000001 1000001 •
-0.5	0	10100001 10100000 11100000
-1.0	0	11000001 1100000 01000000
-1.5	0	01100001 01100000 00100000
-2.0	0	• 00000011 00000001 00000000

VRBF, VRBS, VRTF, VRTS, VRM (Reference Inputs)

There are two reference inputs and one external reference voltage tap. These are -2V (VRB force and sense), mid-tap (VRM), and AGND (VRT force and sense). The reference pins and tap can be driven by op amps (as shown in Figure 1), or VRM can be bypassed for limited temperature operation. These voltage inputs can be bypassed to AGND for further noise suppression, if desired.

Thermal Management

The typical thermal impedance has (θ_{CA}) for the MQUAD package been measured at $\theta_{CA} = 17^{\circ}$ C/W, in still air with no heatsink.

To ensure rated performance, we highly recommend using this device with a heatsink that can provide adequate air flow. We have found that a Thermalloy 17846 heatsink with a minimum air flow of 1 meter/second (200 linear feet per minute) provides adequate thermal performance under laboratory tests. Application-specific conditions should be taken into account to ensure that the device is properly heat sinked.

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MAX1150

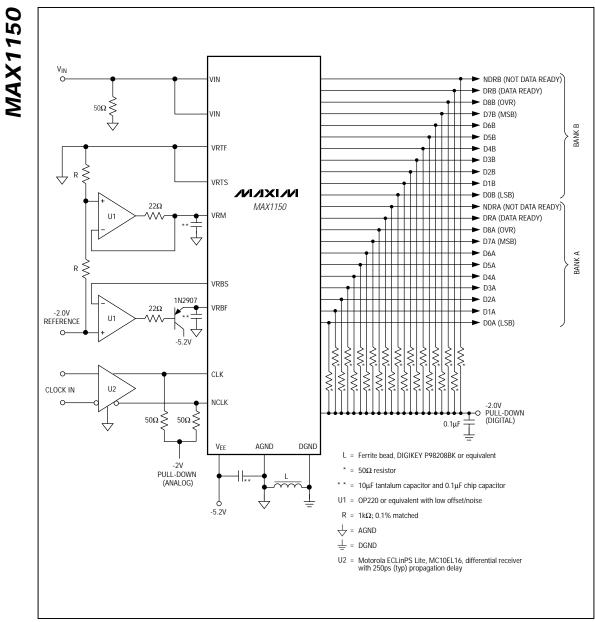


Figure 1. Typical Interface Circuit

M/IXI/M

Operation

The MAX1150 has 255 preamplifier/comparator pairs; each is supplied with the voltage from VRT to VRB, divided equally by the resistive ladder as shown in the Functional Diagram. This voltage is applied to the positive input of each preamplifier/comparator pair. An analog input voltage applied at VIN is connected to the negative inputs of each preamplifier/comparator pair. The comparators are then clocked through each one's individual clock buffer. When the CLK pin is in the low state, the master or input stage of the comparators compares the analog input voltage to the respective reference voltage. When CLK changes from low to high, the comparators are latched to the state prior to the clock transition and output logic codes in sequence from the top comparators, closest to VRT (0V), down to the point where the magnitude of the input signal changes sign (thermometer code). The output of each comparator is then registered into four 64-to-6 bit decoders when CLK is changed from high to low. At the output of the decoders is a set of four 7-bit latches that are enabled (track) when the clock changes from high to low. From here, the output of the latches is coded into six LSBs from four columns, and four columns are coded into two MSBs. Finally, eight ECL output latches and buffers are used to drive the external loads. The conversion takes one clock cycle from the input to the data outputs.

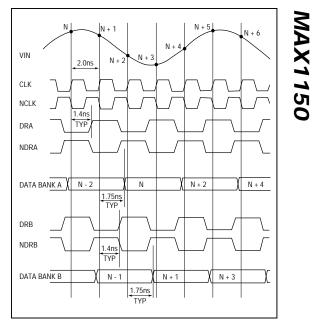


Figure 2. Timing Diagram

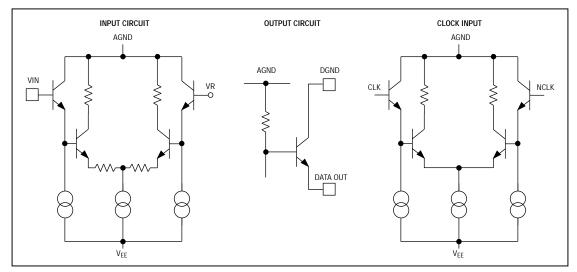
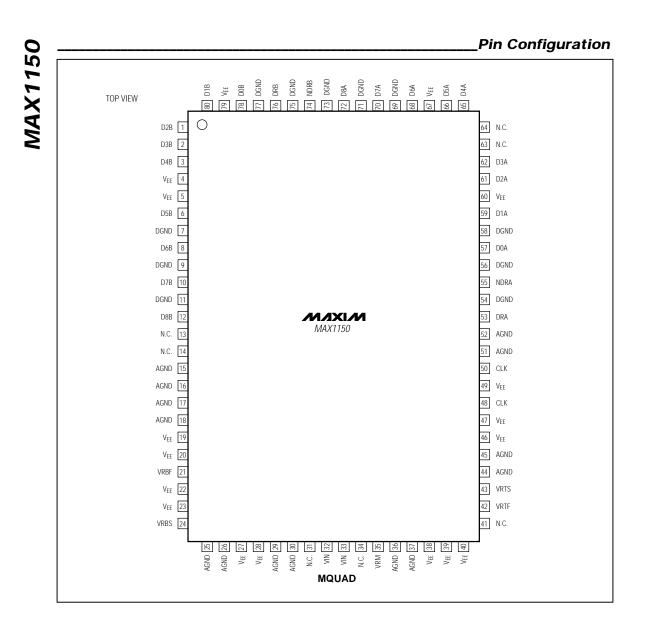


Figure 3. Subcircuit Schematics

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